0.9-Ω SPDT ANALOG SWITCH
5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER

Check for Samples: TS5A3154

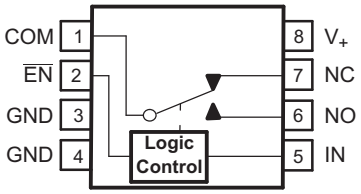
FEATURES

- **Specified Make-Before-Break Switching**
- **Low ON-State Resistance (0.9 Ω)**
- **Control Inputs Are 5.5-V Tolerant**
- **Low Charge Injection**
- **Excellent ON-State Resistance Matching**
- **Low Total Harmonic Distortion (THD)**
- **1.65-V to 5.5-V Single-Supply Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B, Class II)**
  - **1000-V Charged-Device Model (C101)**

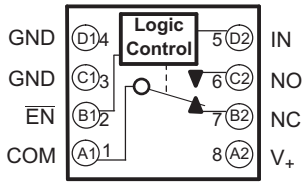
APPLICATIONS

- **Cell Phones**
- **PDAs**
- **Portable Instrumentation**
- **Audio and Video Signal Routing**
- **Low-Voltage Data-Acquisition Systems**
- **Communication Circuits**
- **Modems**
- **Hard Drives**
- **Computer Peripherals**
- **Wireless Terminals and Peripherals**

DCU PACKAGE
(TOP VIEW)



YZP PACKAGE
(BOTTOM VIEW)



DESCRIPTION/ORDERING INFORMATION

The TS5A3154 is a single-pole double-throw (SPDT) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers a low ON-state resistance and an excellent channel-to-channel ON-state resistance matching. The device has excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

Table 1. ORDERING INFORMATION

T_A	PACKAGE(1) (2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING(3)
–40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	TS5A3154YZPR	_ _ _JX_
	SSOP – DCU	Reel of 3000	TS5A3154DCUR	JCF_

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
(3) DCU: The actual top-side marking has one additional character that designates the assembly/test site.
YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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Table 2. FUNCTION TABLE

$\overline{EN}$	IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	L	ON	OFF
L	H	OFF	ON
H	X	OFF	OFF

Table 3. Summary of Characteristics(1)

Configuration	Single-Pole, Double-Throw 2:1 Multiplexer/Demultiplexer (SPDT)
Number of channels	1
ON-state resistance (r_{on})	0.9 Ω
ON-state resistance match (Δr_{on})	0.1 Ω
ON-state resistance flatness ($r_{on(flat)}$)	0.15 Ω
Turn-on/turn-off time (t_{ON}/t_{OFF})	8 ns/12.5 ns
Make-before-break time (t_{MBB})	12 ns
Charge injection (Q_C)	10 pC
Bandwidth (BW)	100 MHz
OFF isolation (O_{ISO})	–64 dB at 1 MHz
Crosstalk (X_{TALK})	–64 dB at 1 MHz
Total harmonic distortion (THD)	0.004%
Leakage current ($I_{COM(OFF)}/I_{NC(OFF)}$)	±20 nA
Power-supply current (I_+)	0.1 µA
Package option	8-pin SSOP or DSBGA

(1) V_+ = 5 V, T_A = 25°C

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Absolute Minimum and Maximum Ratings(1) (2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_+	Supply voltage range(3)		–0.5	6.5	V
V_{NC}, V_{NO}, V_{COM}	Analog voltage range(3) (4) (5)		–0.5	V_+ + 0.5	V
I_K	Analog port diode current	V_{NC}, V_{NO}, V_{COM} < 0 or V_{NO}, V_{NC}, V_{COM} > V_+	–50	50	mA
I_{NC}, I_{COM}, I_{NO}	On-state switch current	V_{NC}, V_{NO}, V_{COM} = 0 to V_+	–200	200	mA
	On-state peak switch current(6)		–400	400	
V_I	Digital input voltage range(3) (4)		–0.5	6.5	V
I_{IK}	Digital input clamp current	V_I < 0	–50		mA
I_+	Continuous current through V_+			100	mA
I_{GND}	Continuous current through GND		–100	100	mA
θ_{JA}	Package thermal impedance(7)	DCU package		227	°C/W
		YZP package		102	
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
(3) All voltages are with respect to ground, unless otherwise specified.
(4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(5) This value is limited to 5.5 V maximum.
(6) Pulse at 1-ms duration < 10% duty cycle.
(7) The package thermal impedance is calculated in accordance with JESD 51-7.

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Electrical Characteristics for 5-V Supply(1)

V_+ = 4.5 V to 5.5 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V_+	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V_{COM}, V_{NO}, V_{NC}					0		V_+	V
Peak ON resistance	r_{peak}	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	4.5 V		0.9	1.1	Ω
				Full				1.3	
ON-state resistance	r_{on}	V_{NO} or V_{NC} = 2.5 V, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	4.5 V		0.8	0.9	Ω
				Full				1.1	
ON-state resistance matching between channels	Δr_{on}	V_{NO} or V_{NC} = 2.5 V, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	4.5 V		0.05	0.1	Ω
				Full				0.1	
ON-state resistance flatness	$r_{on(flat)}$	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	4.5 V		0.15		Ω
				Full					
		V_{NO} or V_{NC} = 1 V, 1.5 V, 2.5 V, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C			0.09	0.15	
				Full				0.15	
NC, NO OFF leakage current	$I_{NC(OFF)}$, $I_{NO(OFF)}$	V_{NC} or V_{NO} = 1 V, V_{COM} = 4.5 V, or V_{NC} or V_{NO} = 4.5 V, V_{COM} = 1 V,	Switch OFF, See Figure 14	25°C	5.5 V	–20	2	20	nA
				Full		–150		150	
	$I_{NC(PWROFF)}$, $I_{NO(PWROFF)}$	V_{NC} or V_{NO} = 0 to 5.5 V, V_{COM} = 5.5 V to 0,	Switch OFF, See Figure 14	25°C	0 V	–5	0.7	5	µA
				Full		–25		25	
NC, NO ON leakage current	$I_{NC(ON)}$, $I_{NO(ON)}$	V_{NC} or V_{NO} = 1 V, V_{COM} = Open, or V_{NC} or V_{NO} = 4.5 V, V_{COM} = Open,	Switch ON, See Figure 15	25°C	5.5 V	–20	2	20	nA
				Full		–150		150	
COM OFF leakage current	$I_{COM(OFF)}$	V_{COM} = 1 V, V_{NC} or V_{NO} = 4.5 V, or V_{COM} = 4.5 V, V_{NC} or V_{NO} = 1 V,	Switch OFF, See Figure 14	25°C	5.5 V	–20	2	20	nA
				Full		–150		150	
	$I_{COM(PWROFF)}$	V_{NC} or V_{NO} = 0 to 5.5 V, V_{COM} = 5.5 V to 0,	Switch OFF, See Figure 14	25°C	0 V	–5	0.7	5	µA
				Full		–25		25	
COM ON leakage current	$I_{COM(ON)}$	V_{COM} = 1 V, V_{NC} or V_{NO} = Open, or V_{COM} = 4.5 V, V_{NC} or V_{NO} = Open,	Switch ON, See Figure 15	25°C	5.5 V	–20	2	20	nA
				Full		–150		150	
Digital Control Inputs (IN, $\overline{EN}$)(2)									
Input logic high	V_{IH}			Full		2.4		5.5	V
Input logic low	V_{IL}			Full		0		0.8	V
Input leakage current	I_{IH}, I_{IL}	V_I = 5.5 V or 0 V		25°C	5.5 V	–100	25	100	nA
				Full		–100		100	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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Electrical Characteristics for 5-V Supply[1] (continued)

V_+ = 4.5 V to 5.5 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V_+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time, IN or $\overline{OE}$	t_{ON}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	5 V	1	5.2	8	ns
				Full	4.5 V to 5.5 V	1		9	
Turn-off time, IN or $\overline{OE}$	t_{OFF}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	5 V	5	9.5	12.5	ns
				Full	4.5 V to 5.5 V	4		13.5	
Make-before-break time	t_{MBB}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 18	25°C	5 V	4	6.3	12	ns
				Full	4.5 V to 5.5 V	4		13	
Charge injection	Q_C	V_{GEN} = 0, R_{GEN} = 0,	C_L = 1 nF, See Figure 22	25°C	5 V		10		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$, $C_{NO(OFF)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch OFF, See Figure 16	25°C	5 V		19		pF
NC, NO ON capacitance	$C_{NC(ON)}$, $C_{NO(ON)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch ON, See Figure 16	25°C	5 V		57		pF
COM OFF capacitance	$C_{COM(OFF)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	5 V		36		pF
COM ON capacitance	$C_{COM(ON)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	5 V		57		pF
Digital input capacitance	C_I	V_I = V_+ or GND,	See Figure 16	25°C	5 V		2		pF
Bandwidth	BW	R_L = 50 Ω,	Switch ON, See Figure 19	25°C	5 V		100		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	5 V		–64		dB
Crosstalk	X_{TALK}	R_L = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	5 V		–64		dB
Total harmonic distortion	THD	R_L = 600 Ω, C_L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	5 V		0.004		%
Supply									
Positive supply current	I_+	V_I = V_+ or GND,	Switch ON or OFF	25°C	5.5 V		0.02	0.1	μA
				Full				0.5	

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Electrical Characteristics for 3.3-V Supply(1)

V_+ = 3 V to 3.6 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V+	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V_{COM}, V_{NO}, V_{NC}					0		V_+	V
Peak ON resistance	r_{peak}	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	3 V		1.3	1.6	Ω
				Full				1.9	
ON-state resistance	r_{on}	V_{NO} or V_{NC} = 2 V, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	3 V		1.2	1.5	Ω
				Full				1.7	
ON-state resistance match between channels	Δr_{on}	V_{NO} or V_{NC} = 2 V, 0.8 V I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	3 V		0.08	0.15	Ω
				Full				0.15	
ON-state resistance flatness	$r_{on(flat)}$	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C	3 V		0.3		Ω
				Full					
		V_{NO} or V_{NC} = 2 V, 0.8 V, I_{COM} = –100 mA,	Switch ON, See Figure 13	25°C			0.09	0.15	
				Full				0.15	
NC, NO OFF leakage current	$I_{NC(OFF)}$, $I_{NO(OFF)}$	V_{NC} or V_{NO} = 1 V, V_{COM} = 3 V, or V_{NC} or V_{NO} = 3 V, V_{COM} = 1 V,	Switch OFF, See Figure 14	25°C	3.6 V	–20	2	20	nA
				Full		–50		50	
	$I_{NC(PWROFF)}$, $I_{NO(PWROFF)}$	V_{NC} or V_{NO} = 0 to 3.6 V, V_{COM} = 3.6 V to 0 V,	Switch OFF, See Figure 14	25°C	0 V	–1	0.2	1	µA
				Full		–15		15	
NC, NO ON leakage current	$I_{NC(ON)}$, $I_{NO(ON)}$	V_{NC} or V_{NO} = 1 V, V_{COM} = Open, or V_{NC} or V_{NO} = 3 V, V_{COM} = Open,	Switch ON, See Figure 15	25°C	3.6 V	–20	2	20	nA
				Full		–50		50	
COM OFF leakage current	$I_{COM(OFF)}$	V_{COM} = 1 V, V_{NC} or V_{NO} = 3 V, or V_{COM} = 3 V, V_{NC} or V_{NO} = 1 V,	Switch OFF, See Figure 14	25°C	3.6 V	–20	2	20	nA
				Full		–50		50	
	$I_{COM(PWROFF)}$	V_{NC} or V_{NO} = 0 to 3.6 V, V_{COM} = 3.6 V to 0,	Switch OFF, See Figure 14	25°C	0 V	–1	0.2	1	µA
				Full		–15		15	
COM ON leakage current	$I_{COM(ON)}$	V_{COM} = 1 V, V_{NC} or V_{NO} = Open, or V_{COM} = 3 V, V_{NC} or V_{NO} = Open	Switch ON, See Figure 15	25°C	3.6 V	–20	2	20	nA
				Full		–50		50	
Digital Control Inputs (IN, $\overline{EN}$)(2)									
Input logic high	V_{IH}			Full		2		5.5	V
Input logic low	V_{IL}			Full		0		0.8	V
Input leakage current	I_{IH}, I_{IL}	V_I = 5.5 V or 0		25°C	3.6 V	–100	25	100	nA
				Full		–100		100	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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Electrical Characteristics for 3.3-V Supply(1) (continued)

V_+ = 3 V to 3.6 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time, IN or $\overline{OE}$	t_{ON}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	3.3 V	3	6	10	ns
				Full	3 V to 3.6 V	2		10.5	
Turn-off time, IN or $\overline{OE}$	t_{OFF}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	3.3 V	5	10	15	ns
				Full	3 V to 3.6 V	4		17	
Make-before-break time	t_{MBB}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 18	25°C	3.3 V	4	5.7	12	ns
				Full	3 V to 3.6 V	4		13	
Charge injection	Q_C	V_{GEN} = 0, R_{GEN} = 0,	C_L = 1 nF, See Figure 22	25°C	3.3 V		9		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$, $C_{NO(OFF)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch OFF, See Figure 16	25°C	3.3 V		19		pF
NC, NO ON capacitance	$C_{NC(ON)}$, $C_{NO(ON)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch ON, See Figure 16	25°C	3.3 V		57		pF
COM OFF capacitance	$C_{COM(OFF)}$	V_{COM} = V_+ or GND,	Switch ON, See	25°C	3.3 V		36		pF
COM ON capacitance	$C_{COM(ON)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	3.3 V		57		pF
Digital input capacitance	C_I	V_I = V_+ or GND,	See Figure 16	25°C	3.3 V		2		pF
Bandwidth	BW	R_L = 50 Ω,	Switch ON, See Figure 19	25°C	3.3 V		100		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	3.3 V		–64		dB
Crosstalk	X_{TALK}	R_L = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	3.3 V		–64		dB
Total harmonic distortion	THD	R_L = 600 Ω, C_L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	3.3 V		0.01 0		%
Supply									
Positive supply current	I_+	V_I = V_+ or GND,	Switch ON or OFF	25°C	3.6 V		0.01	0.1	µA
				Full				0.25	

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Electrical Characteristics for 2.5-V Supply(1)

V_+ = 3 V to 3.6 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V_+	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V_{COM}, V_{NO}, V_{NC}					0		V_+	V
Peak ON resistance	r_{peak}	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –8 mA,	Switch ON, See Figure 13	25°C	2.3 V		1.9	2.5	Ω
				Full				2.7	
ON-state resistance	r_{on}	V_{NO} or V_{NC} = 1.8 V, I_{COM} = –8 mA,	Switch ON, See Figure 13	25°C	2.3 V		1.6	2.1	Ω
				Full				2.5	
ON-state resistance matching between channels	Δr_{on}	V_{NO} or V_{NC} = 1.8 V, I_{COM} = –8 mA,	Switch ON, See Figure 13	25°C	2.3 V		0.12	0.2	Ω
				Full				0.2	
ON-state resistance flatness	$r_{on(flat)}$	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –8 mA,	Switch ON, See Figure 13	25°C	2.3 V		0.65		Ω
				Full					
		V_{NO} or V_{NC} = 0.8 V, 1.8 V, I_{COM} = –8 mA,	Switch ON, See Figure 13	25°C			0.5	1	
				Full				1	
NC, NO OFF leakage current	$I_{NC(OFF)}$, $I_{NO(OFF)}$	V_{NC} or V_{NO} = 0.5 V, V_{COM} = 2.3 V, or V_{NC} or V_{NO} = 2.3 V, V_{COM} = 0.5 V,	Switch OFF, See Figure 14	25°C	2.7 V	–20	2	20	nA
				Full		–50		50	
	$I_{NC(PWROFF)}$, $I_{NO(PWROFF)}$	V_{NC} or V_{NO} = 0 to 2.7 V, V_{COM} = 2.7 V to 0,	Switch OFF, See Figure 14	25°C	0 V	–1		1	µA
				Full		–10		10	
NC, NO ON leakage current	$I_{NC(ON)}$, $I_{NO(ON)}$	V_{NC} or V_{NO} = 0.5 V, V_{COM} = Open, or V_{NC} or V_{NO} = 2.3 V, V_{COM} = Open,	Switch ON, See Figure 15	25°C	2.7 V	–20		20	nA
				Full		–50		50	
COM OFF leakage current	$I_{COM(OFF)}$	V_{COM} = 0.5 V, V_{NC} or V_{NO} = 2.3 V, or V_{COM} = 2.3 V, V_{NC} or V_{NO} = 0.5V,	Switch OFF, See Figure 14	25°C	2.7 V	–20		20	nA
				Full		–50		50	
	$I_{COM(PWROFF)}$	V_{NC} or V_{NO} = 0 to 2.7 V, V_{COM} = 2.7 V to 0,	Switch OFF, See Figure 14	25°C	0 V	–1		1	µA
				Full		–10		10	
COM ON leakage current	$I_{COM(ON)}$	V_{COM} = 0.5 V, V_{NC} or V_{NO} = Open, or V_{COM} = 2.3 V, V_{NC} or V_{NO} = Open,	Switch ON, See Figure 15	25°C	2.7 V	–20		20	nA
				Full		–50		50	
Digital Control Inputs (IN, $\overline{EN}$)(2)									
Input logic high	V_{IH}			Full		1.8		5.5	V
Input logic low	V_{IL}			Full		0		0.6	V
Input leakage current	I_{IH}, I_{IL}	V_I = 5.5 V or 0		25°C	2.7 V	–100	25	100	nA
				Full		–100		100	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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Electrical Characteristics for 2.5-V Supply(1) (continued)

V_+ = 3 V to 3.6 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V_+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time, IN or $\overline{OE}$	t_{ON}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	2.5 V	4	7.0	11.5	ns
				Full	2.3 V to 2.7 V	3.5		12	
Turn-off time, IN or $\overline{OE}$	t_{OFF}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	2.5 V	5	11.5	18.5	ns
				Full	2.3 V to 2.7 V	4		21	
Make-before-break time	t_{MBB}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 18	25°C	2.5 V	4	6.3	15	ns
				Full	2.3 V to 2.7 V	4		16	
Charge injection	Q_C	V_{GEN} = 0, R_{GEN} = 0,	C_L = 1 nF, See Figure 22	25°C	2.5 V		7		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$, $C_{NO(OFF)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch OFF, See Figure 16	25°C	2.5 V		19		pF
NC, NO ON capacitance	$C_{NC(ON)}$, $C_{NO(ON)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch ON, See Figure 16	25°C	2.5 V		57		pF
COM OFF capacitance	$C_{COM(OFF)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	2.5 V		36		pF
COM ON capacitance	$C_{COM(ON)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	2.5 V		57		pF
Digital input capacitance	C_I	V_I = V_+ or GND,	See Figure 16	25°C	2.5 V		2		pF
Bandwidth	BW	R_L = 50 Ω,	Switch ON, See Figure 19	25°C	2.5 V		100		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	2.5 V		–64		dB
Crosstalk	X_{TALK}	R_L = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	2.5 V		–64		dB
Total harmonic distortion	THD	R_L = 600 Ω, C_L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	2.5 V		0.020		%
Supply									
Positive supply current	I_+	V_I = V_+ or GND,	Switch ON or OFF	25°C	2.7 V		0.001	0.05	μA
				Full				0.15	

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Electrical Characteristics for 1.8-V Supply(1)

V_+ = 1.65 V to 1.95 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V_+	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V_{COM}, V_{NO}, V_{NC}					0		V_+	V
Peak ON resistance	r_{peak}	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –2 mA,	Switch ON, See Figure 13	25°C	1.65 V		5.5	25	Ω
				Full				30	
ON-state resistance	r_{on}	V_{NO} or V_{NC} = 1.5 V, I_{COM} = –2 mA,	Switch ON, See Figure 13	25°C	1.65 V		2	2.7	Ω
				Full				3.1	
ON-state resistance matching between channels	Δr_{on}	V_{NO} or V_{NC} = 1.5 V, I_{COM} = –2 mA,	Switch ON, See Figure 13	25°C	1.65 V		0.16	0.3	Ω
				Full				0.3	
ON-state resistance flatness	$r_{on(flat)}$	0 ≤ (V_{NO} or V_{NC}) ≤ V_+, I_{COM} = –2 mA,	Switch ON, See Figure 13	25°C	1.65 V		3		Ω
		V_{NO} or V_{NC} = 0.6 V, 1.5 V, I_{COM} = –2 mA,	Switch ON, See Figure 13	25°C			3	20	
				Full				25	
NC, NO OFF leakage current	$I_{NC(OFF)}$, $I_{NO(OFF)}$	V_{NC} or V_{NO} = 0.3 V, V_{COM} = 1.65 V, or V_{NC} or V_{NO} = 1.65 V, V_{COM} = 0.3 V,	Switch OFF, See Figure 14	25°C	1.95 V	–20	1.5	20	nA
				Full		–50		50	
	$I_{NC(PWROFF)}$, $I_{NO(PWROFF)}$	V_{NC} or V_{NO} = 0 to 1.95 V, V_{COM} = 1.95 V to 0,	Switch OFF, See Figure 14	25°C	0 V	–1	0.1	1	µA
				Full		–10		10	
NC, NO ON leakage current	$I_{NC(ON)}$, $I_{NO(ON)}$	V_{NC} or V_{NO} = 0.3 V, V_{COM} = Open, or V_{NC} or V_{NO} = 1.65 V, V_{COM} = Open,	Switch ON, See Figure 15	25°C	1.95 V	–20	1.5	20	nA
				Full		–50		50	
COM OFF leakage current	$I_{COM(OFF)}$	V_{NC} or V_{NO} = 1.65 V, V_{COM} = 0.3 V, or V_{NC} or V_{NO} = 0.3 V, V_{COM} = 1.65 V,	Switch OFF, See Figure 14	25°C	1.95 V	–20	1.5	20	nA
				Full		–50		50	
	$I_{COM(PWROFF)}$	V_{NC} or V_{NO} = 1.95 V to 0, V_{COM} = 0 to 1.95 V,	Switch OFF, See Figure 14	25°C	0 V	–1	0.06	1	µA
				Full		–10		10	
COM ON leakage current	$I_{COM(ON)}$	V_{NC} or V_{NO} = Open, V_{COM} = 0.3 V, or V_{NC} or V_{NO} = Open, V_{COM} = 1.65 V,	Switch ON, See Figure 15	25°C	1.95 V	–20	1.5	20	nA
				Full		–50		50	
Digital Control Inputs (IN, $\overline{EN}$)(2)									
Input logic high	V_{IH}			Full		1.5		5.6	V
Input logic low	V_{IL}			Full		0		0.6	V
Input leakage current	I_{IH}, I_{IL}	V_I = 5.5 V or 0		25°C	1.95 V	–100	25	100	nA
				Full		–100		100	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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Electrical Characteristics for 1.8-V Supply(1) (continued)

V_+ = 1.65 V to 1.95 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_A	V_+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time, IN or $\overline{OE}$	t_{ON}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	5 V	5		20.5	ns
				Full	1.65 V to 1.95 V	4.5		21	
Turn-off time, IN or $\overline{OE}$	t_{OFF}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 17	25°C	5 V	7	16.5	27.5	ns
				Full	1.65 V to 1.95 V	5		30	
Make-before-break time	t_{MBB}	V_{COM} = V_+, R_L = 50 Ω,	C_L = 35 pF, See Figure 18	25°C	5 V	4	8.3	15	ns
				Full	1.65 V to 1.95 V	4		16	
Charge injection	Q_C	V_{GEN} = 0, R_{GEN} = 0,	C_L = 1 nF, See Figure 22	25°C	1.8 V		5		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$, $C_{NO(OFF)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch OFF, See Figure 16	25°C	1.8 V		19		pF
NC, NO ON capacitance	$C_{NC(ON)}$, $C_{NO(ON)}$	V_{NC} or V_{NO} = V_+ or GND,	Switch ON, See Figure 16	25°C	1.8 V		57		pF
COM OFF capacitance	$C_{COM(OFF)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	1.8 V		36		pF
COM ON capacitance	$C_{COM(ON)}$	V_{COM} = V_+ or GND,	Switch ON, See Figure 16	25°C	1.8 V		57		pF
Digital input capacitance	C_I	V_I = V_+ or GND,	See Figure 16	25°C	1.8 V		2.0		pF
Bandwidth	BW	R_L = 50 Ω,	Switch ON, See Figure 19	25°C	1.8 V		100		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	1.8 V		–64		dB
Crosstalk	X_{TALK}	R_L = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	1.8 V		–64		dB
Total harmonic distortion	THD	R_L = 600 Ω, C_L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	1.8 V		0.060		%
Supply									
Positive supply current	I_+	V_I = V_+ or GND,	Switch ON or OFF	25°C	1.95 V		0.001	0.05	µA
				Full				0.1	

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TYPICAL PERFORMANCE

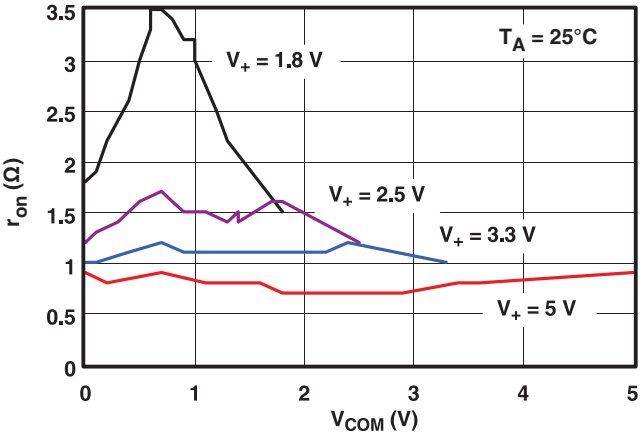


Figure 1. r_{on} vs V_{COM}

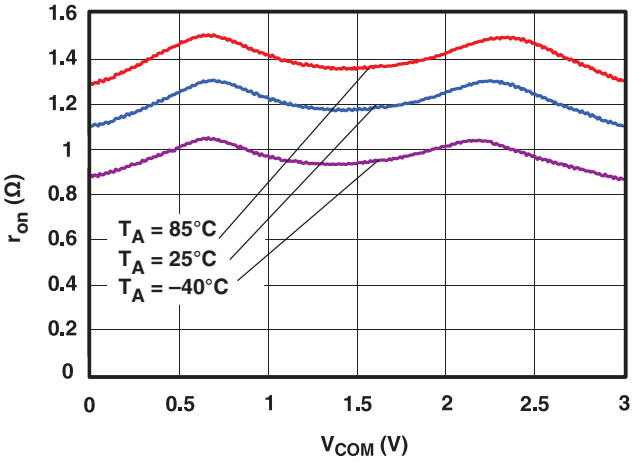


Figure 2. r_{on} vs V_{COM} (V_+ = 3 V)

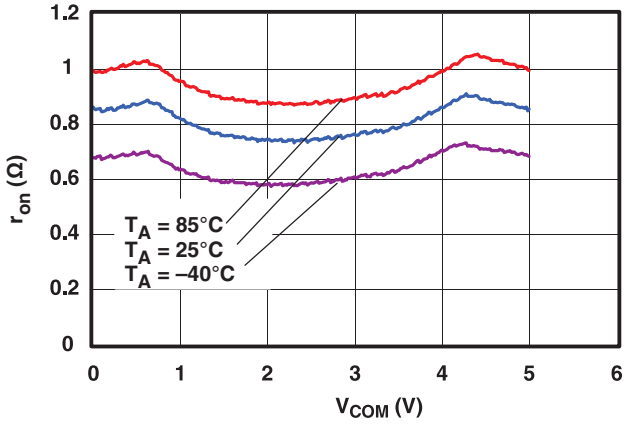


Figure 3. r_{on} vs V_{COM} (V_+ = 5 V)

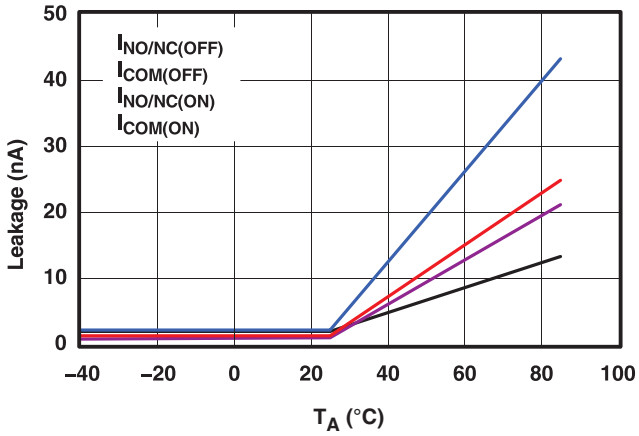


Figure 4. Leakage Current vs Temperature (V_+ = 5.5 V)

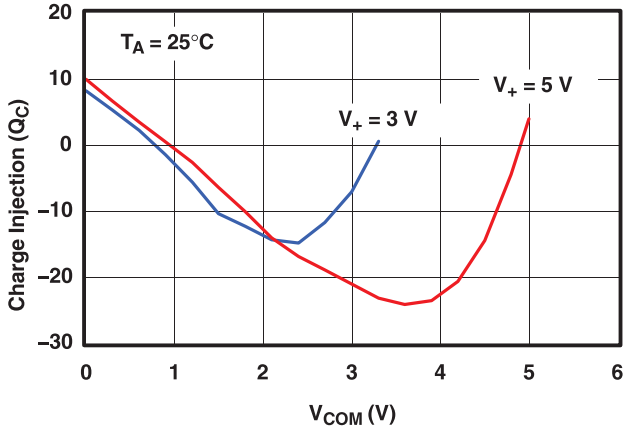


Figure 5. Charge Injection (Q_C) vs V_{COM}

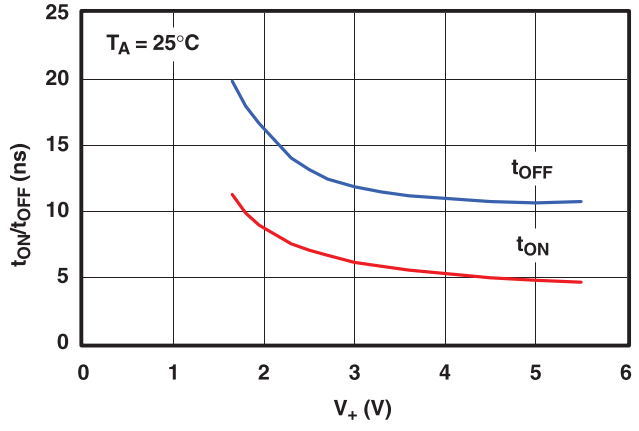


Figure 6. t_{ON} and t_{OFF} vs Supply Voltage

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TYPICAL PERFORMANCE (continued)

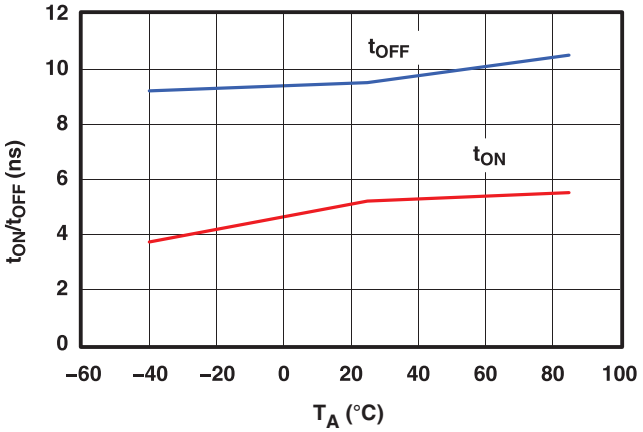


Figure 7. t_{ON} and t_{OFF} vs Temperature (V_+ = 5 V)

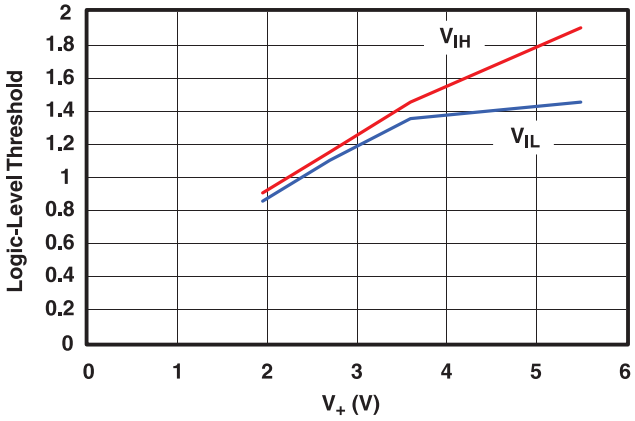


Figure 8. Logic-Level Threshold vs V_+

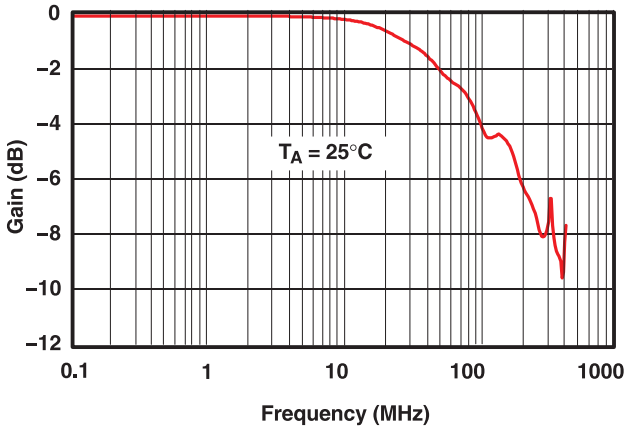


Figure 9. Bandwidth (V_+ = 5 V)

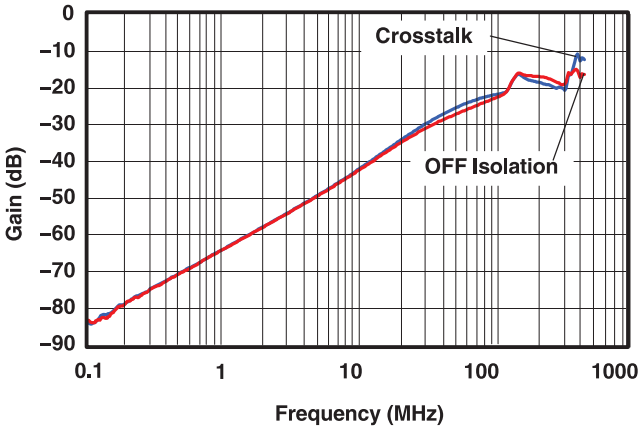


Figure 10. OFF Isolation and Crosstalk (V_+ = 5 V)

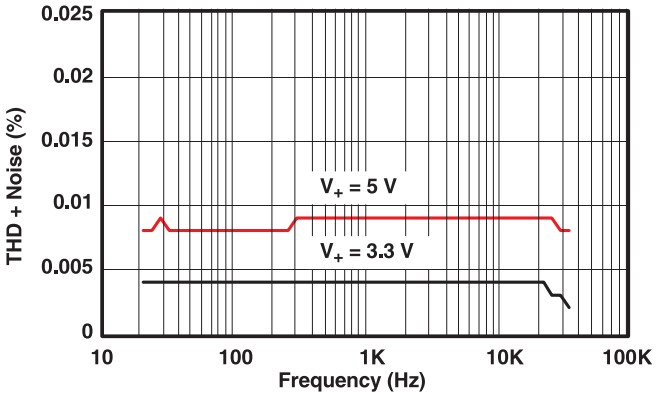


Figure 11. Total Harmonic Distortion (THD) vs Frequency

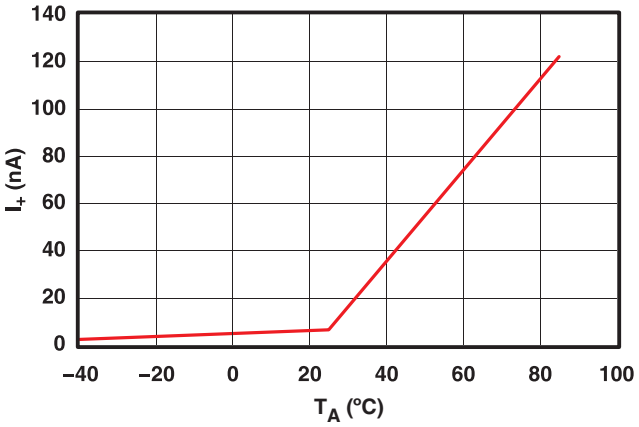


Figure 12. Power Supply Current vs Temperature (V_+ = 5 V)

PIN DESCRIPTION

PIN NO.	NAME	DESCRIPTION
1	COM	Common
2	$\overline{EN}$	Enable control input
3	GND	Digital ground
4	GND	Digital ground
5	IN	Digital control to connect the COM to NO or NC
6	NO	Normally open
7	NC	Normally closed
8	V_+	Power supply

PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
V_{COM}	Voltage at COM
V_{NC}	Voltage at NC
V_{NO}	Voltage at NO
r_{on}	Resistance between COM and NC or COM and NO ports when the channel is ON
Δr_{on}	Difference of r_{on} between channels in a specific device
$r_{on(flat)}$	Difference between the maximum and minimum value of r_{on} in a channel over the specified range of conditions
$I_{NC(OFF)}$	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state
$I_{NO(OFF)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state
$I_{NC(ON)}$	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open
$I_{NO(ON)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
$I_{COM(ON)}$	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) open
V_{IH}	Minimum input voltage for logic high for the control input (IN)
V_{IL}	Maximum input voltage for logic low for the control input (IN)
V_I	Voltage at the control input (IN)
I_{IH}, I_{IL}	Leakage current measured at the control input (IN)
t_{ON}	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning ON.
t_{OFF}	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning OFF.
t_{BBM}	Break-before-make time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
Q_C	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC, NO, or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$, C_L is the load capacitance and ΔV_{COM} is the change in analog output voltage.
$C_{NC(OFF)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
$C_{NO(OFF)}$	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
$C_{NC(ON)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
$C_{NO(ON)}$	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
$C_{COM(ON)}$	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
C_I	Capacitance of control input (IN)
O_{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
X_{TALK}	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency where the gain of an ON channel is –3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of fundamental harmonic.

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PARAMETER DESCRIPTION (continued)

SYMBOL	DESCRIPTION
I_+	Static power-supply current with the control (IN) pin at V_+ or GND

PARAMETER MEASUREMENT INFORMATION

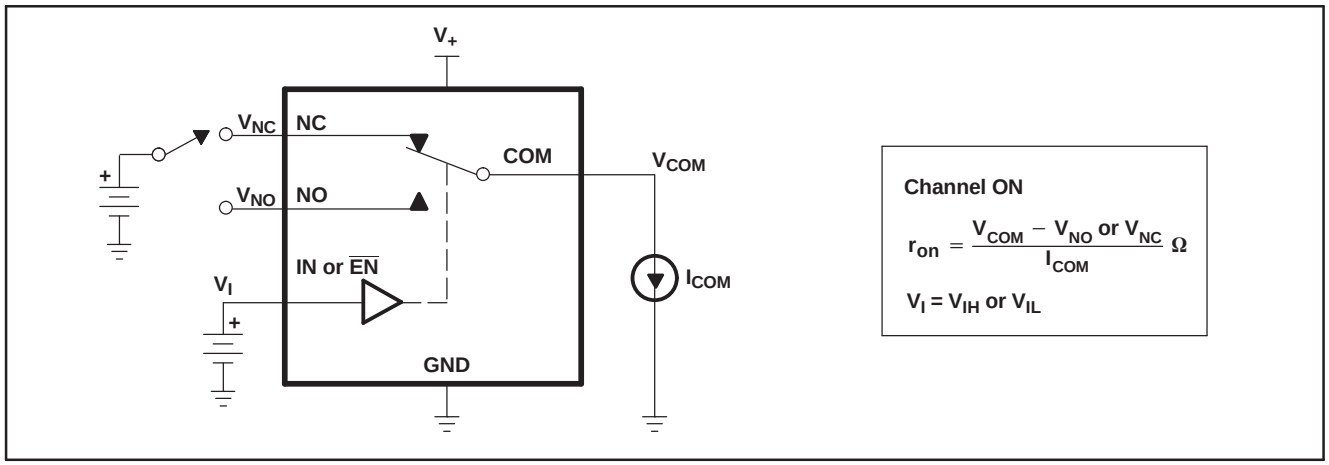


Figure 13. ON-State Resistance (r_{on})

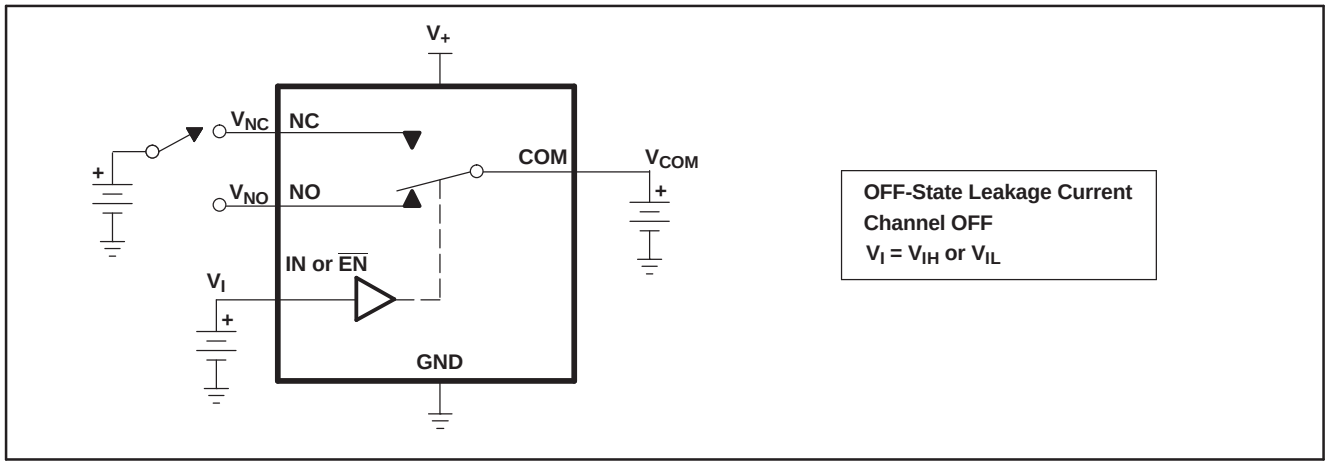


Figure 14. OFF-State Leakage Current ($I_{NC(OFF)}$, $I_{NO(OFF)}$, $I_{NO(PWROFF)}$, $I_{COM(PWROFF)}$)

PARAMETER MEASUREMENT INFORMATION (continued)

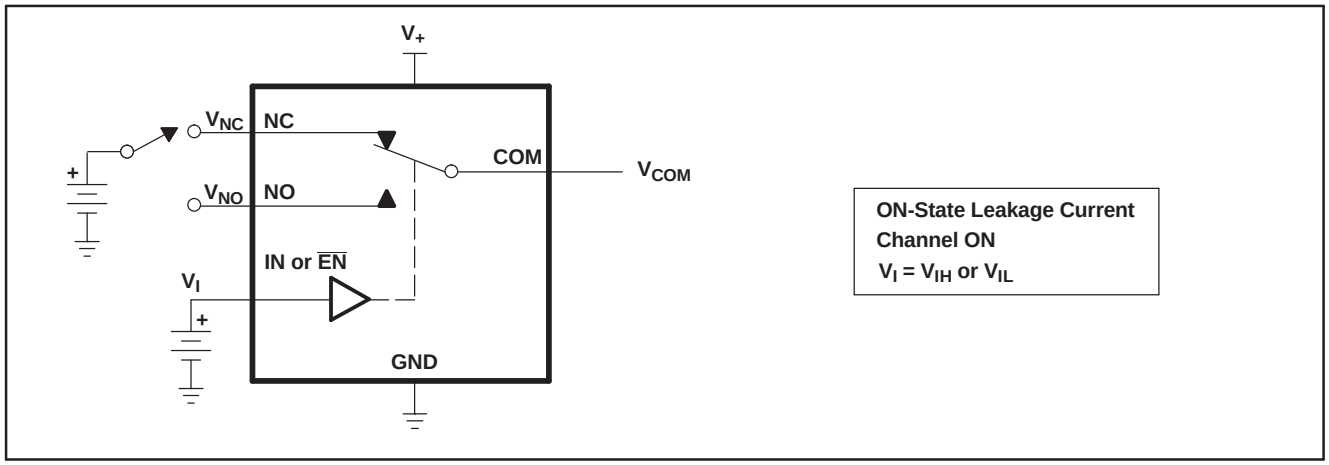


Figure 15. ON-State Leakage Current ($I_{COM(ON)}$, $I_{NC(ON)}$, $I_{NO(ON)}$)

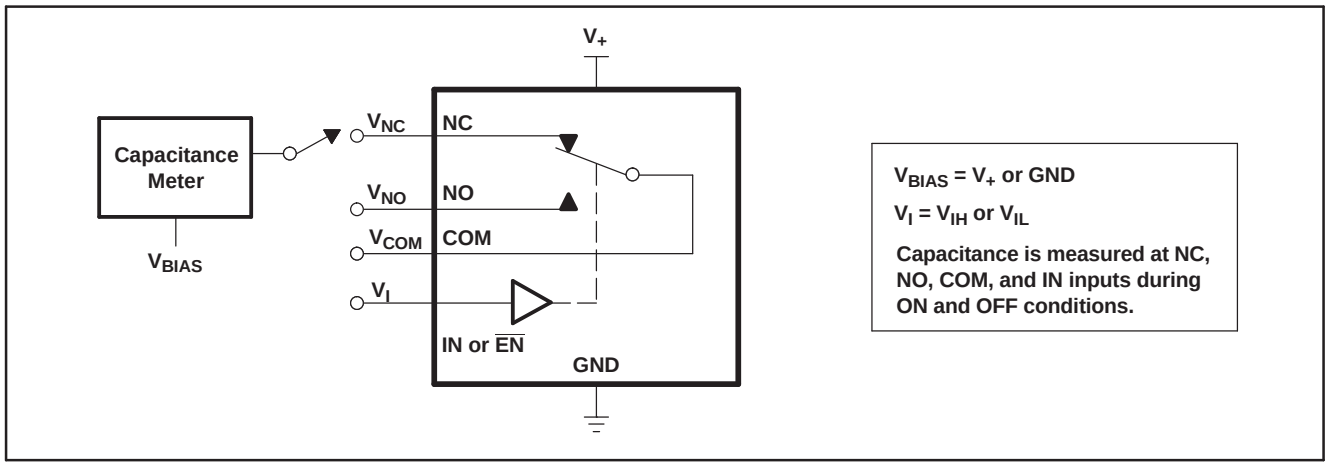
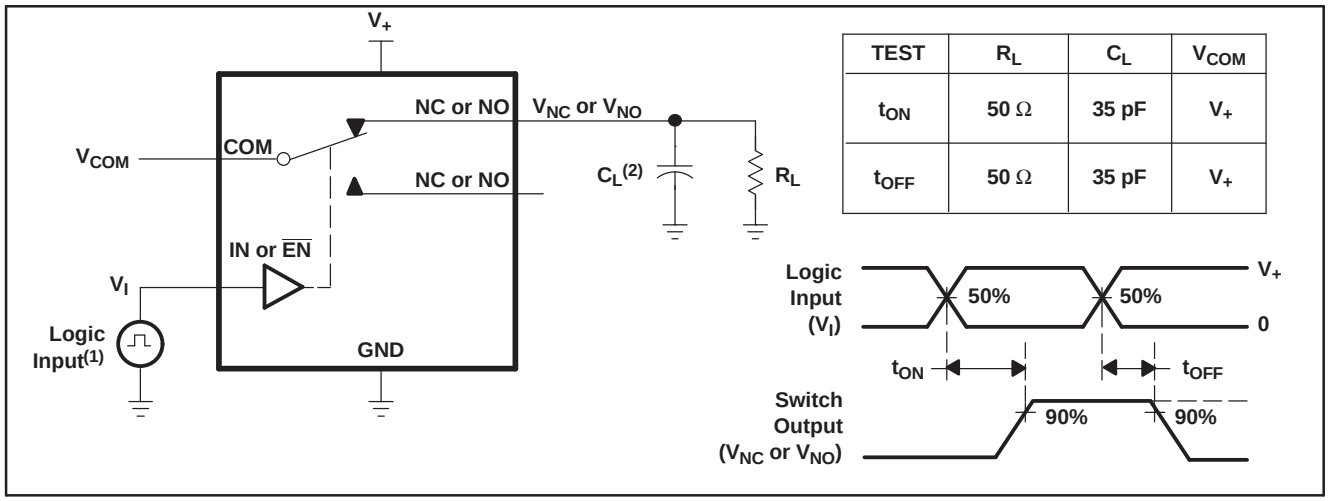


Figure 16. Capacitance (C_I, $C_{COM(OFF)}$, $C_{COM(ON)}$, $C_{NC(OFF)}$, $C_{NO(OFF)}$, $C_{NC(ON)}$, $C_{NO(ON)}$)



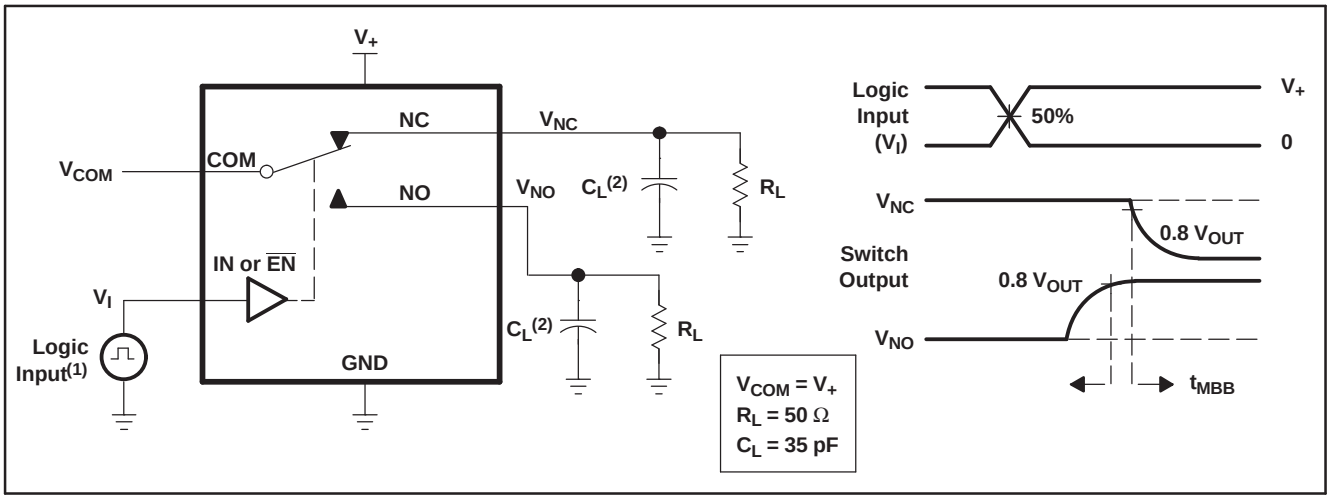
TEST	R_L	C_L	V_{COM}
t_{ON}	50 Ω	35 pF	V_+
t_{OFF}	50 Ω	35 pF	V_+

(1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r < 5 ns, t_f < 5 ns.
(2) C_L includes probe and jig capacitance.

Figure 17. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})

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PARAMETER MEASUREMENT INFORMATION (continued)



(1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r < 5 ns, t_f < 5 ns.
(2) C_L includes probe and jig capacitance.

Figure 18. Make-Before-Break Time (t_{MBB})

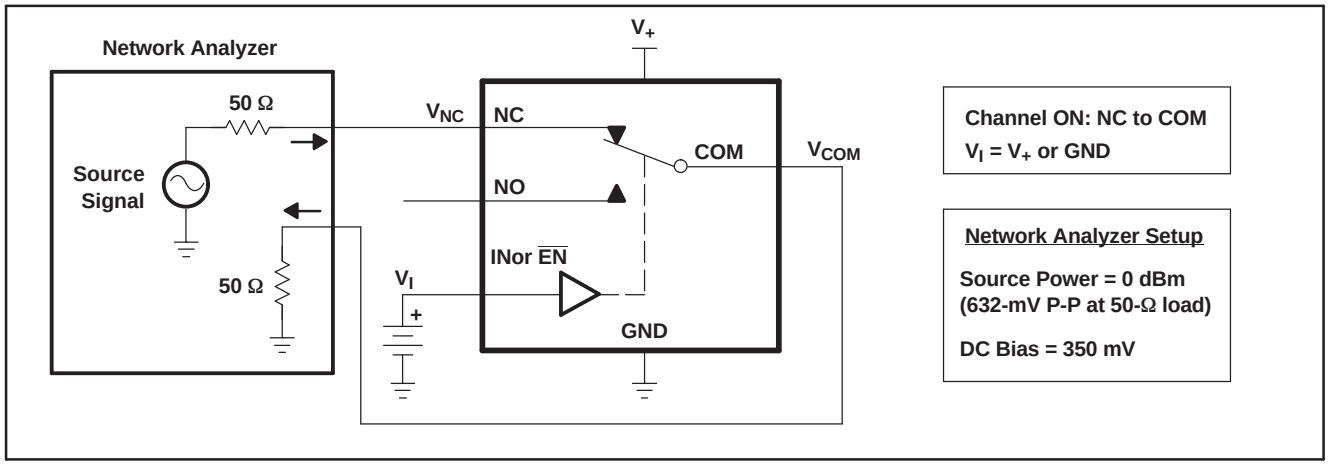


Figure 19. Bandwidth (BW)

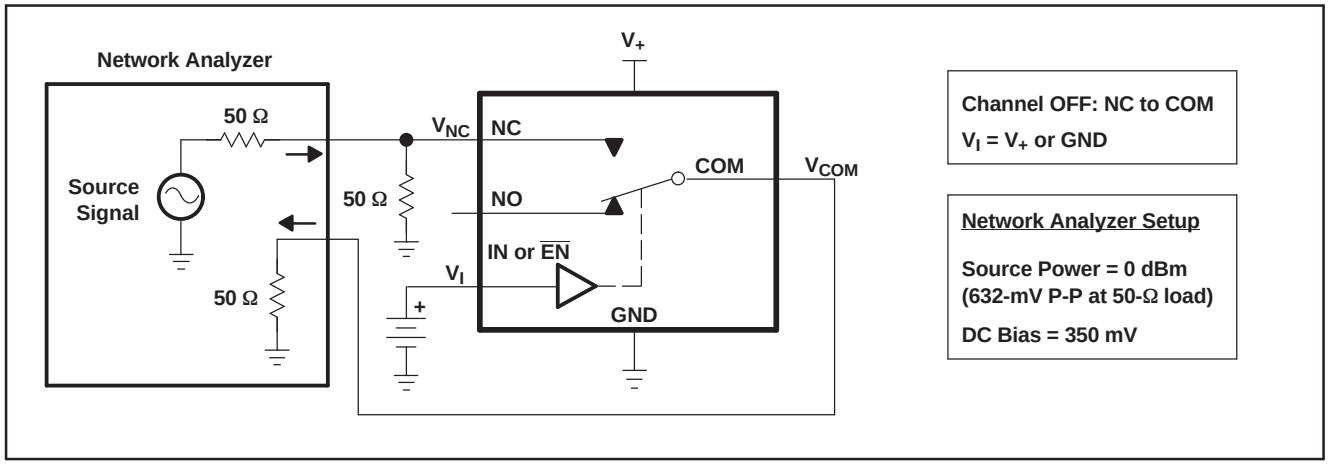


Figure 20. OFF Isolation (O_{ISO})

PARAMETER MEASUREMENT INFORMATION (continued)

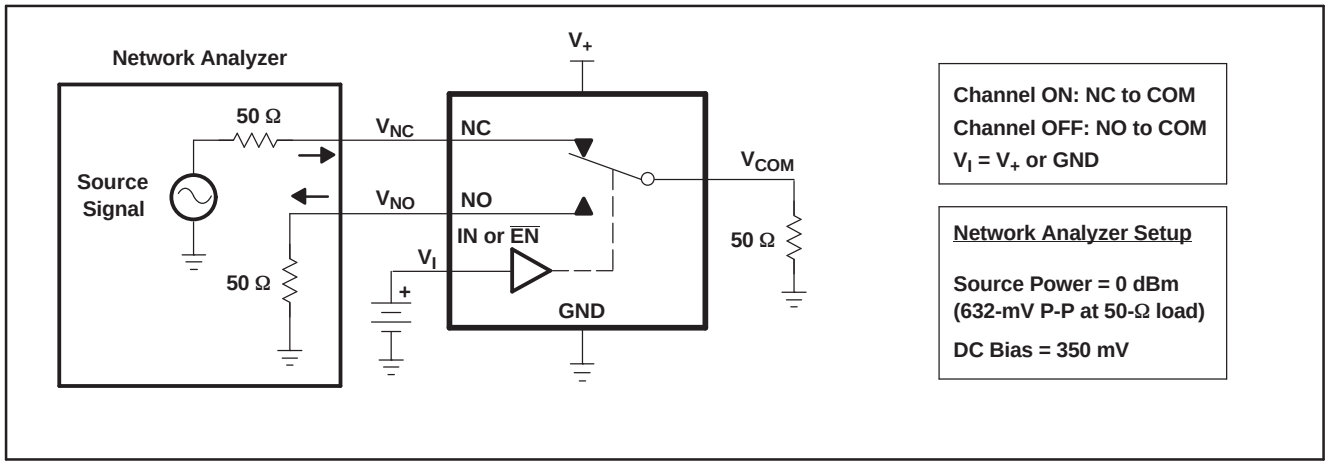
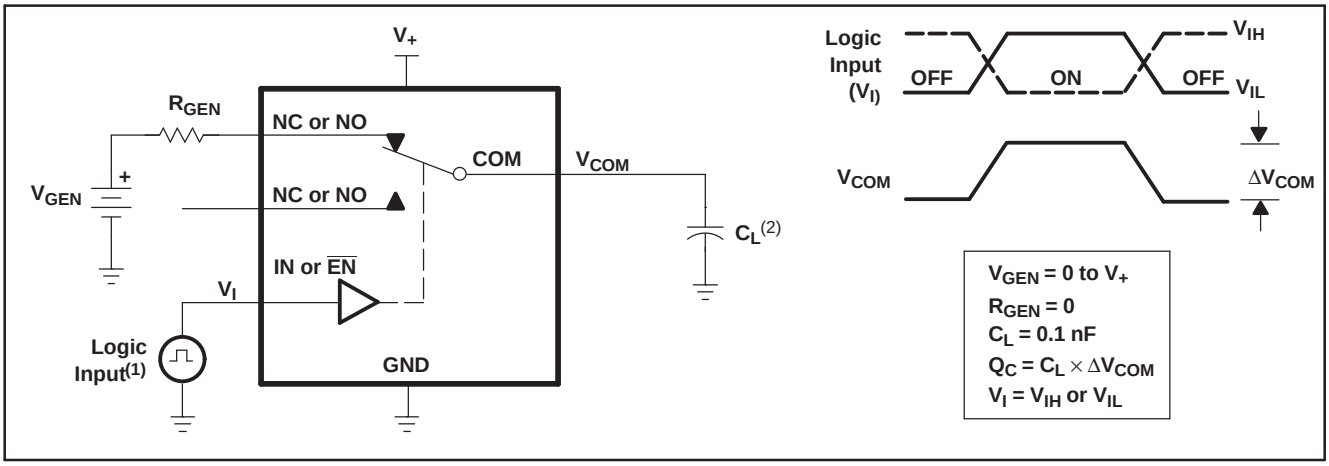


Figure 21. Crosstalk (X_{TALK})

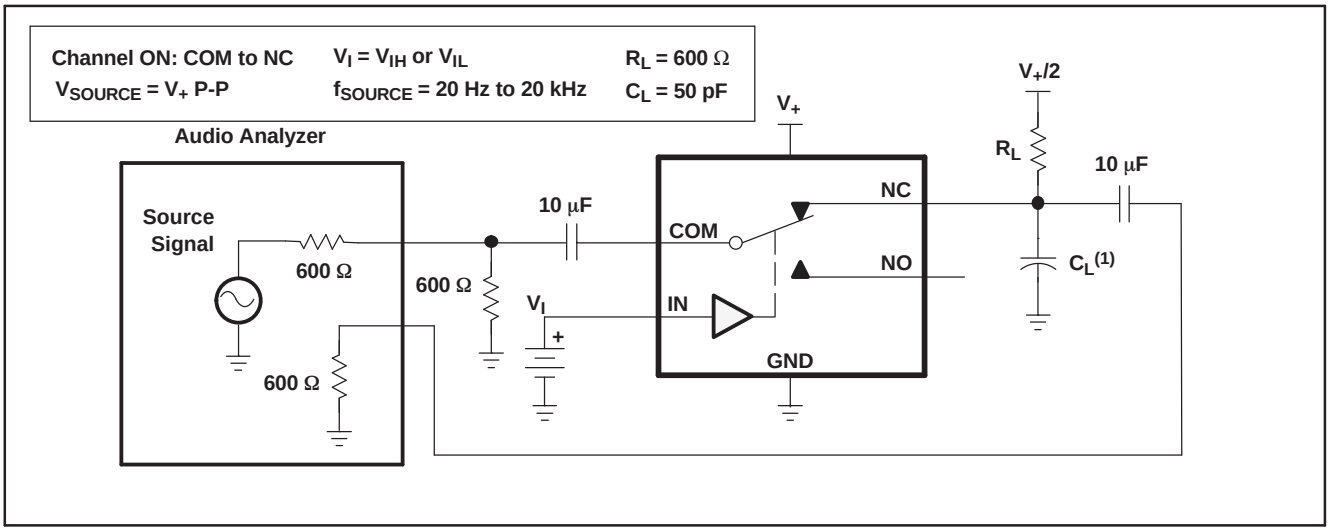


(1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r < 5 ns, t_f < 5 ns.
(2) C_L includes probe and jig capacitance.

Figure 22. Charge Injection (Q_C)

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PARAMETER MEASUREMENT INFORMATION (continued)



(1) C_L includes probe and jig capacitance.

Figure 23. Total Harmonic Distortion (THD)

REVISION HISTORY

Changes from Revision B (May 2009) to Revision C	Page
• Changed ORDERING INFORMATION Table.	1

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TS5A3154DCUR	Active	Production	VSSOP (DCU) | 8	3000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	(CF, JCFQ, JCFR) JZ
TS5A3154DCUR.B	Active	Production	VSSOP (DCU) | 8	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(CF, JCFQ, JCFR) JZ
TS5A3154DCURE6	Preview	Production	VSSOP (DCU) | 8	3000 | null	-	Call TI	Call TI	-40 to 85	
TS5A3154DCURG4	Active	Production	VSSOP (DCU) | 8	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	JCFR
TS5A3154DCURG4.B	Active	Production	VSSOP (DCU) | 8	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	JCFR
TS5A3154YZPR	Active	Production	DSBGA (YZP) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	JXN
TS5A3154YZPR.B	Active	Production	DSBGA (YZP) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	JXN

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

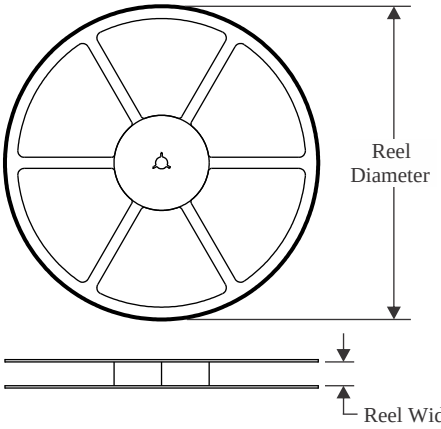
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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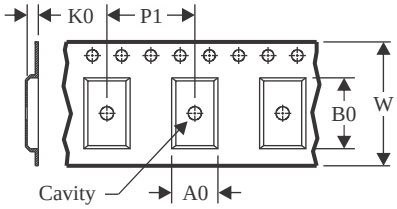
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

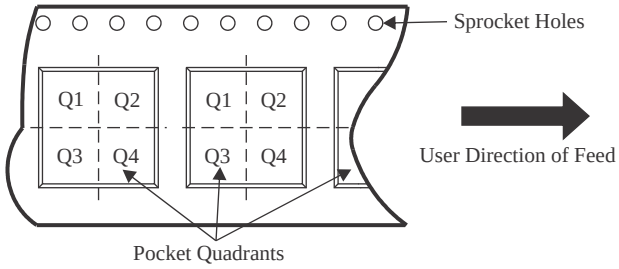


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

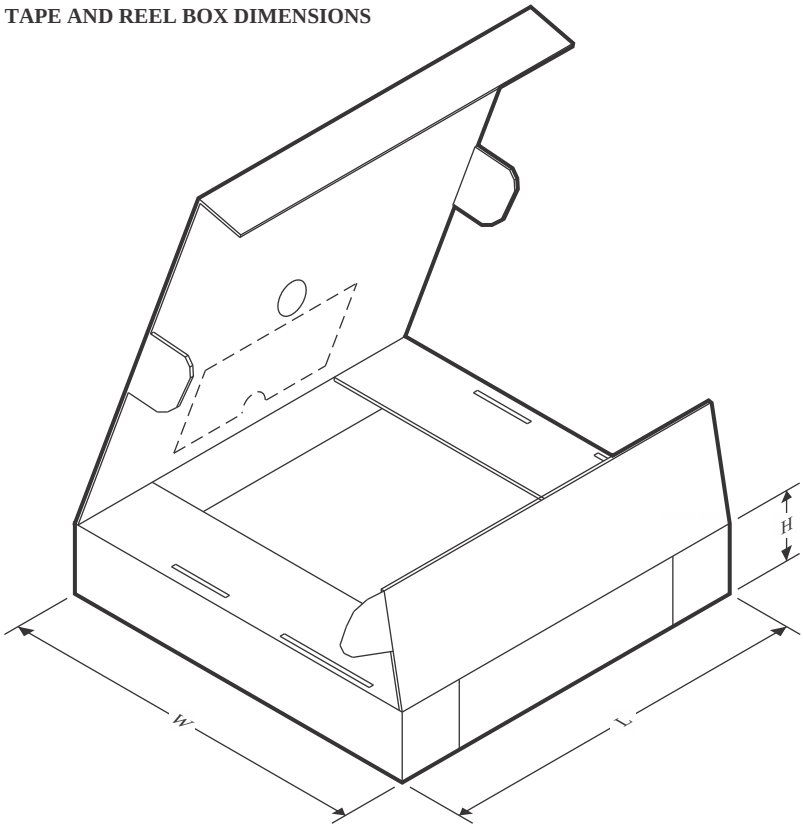
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A3154DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
TS5A3154DCUR	VSSOP	DCU	8	3000	178.0	9.5	2.25	3.35	1.05	4.0	8.0	Q3
TS5A3154DCURG4	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
TS5A3154YZPR	DSBGA	YZP	8	3000	178.0	9.2	1.02	2.02	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

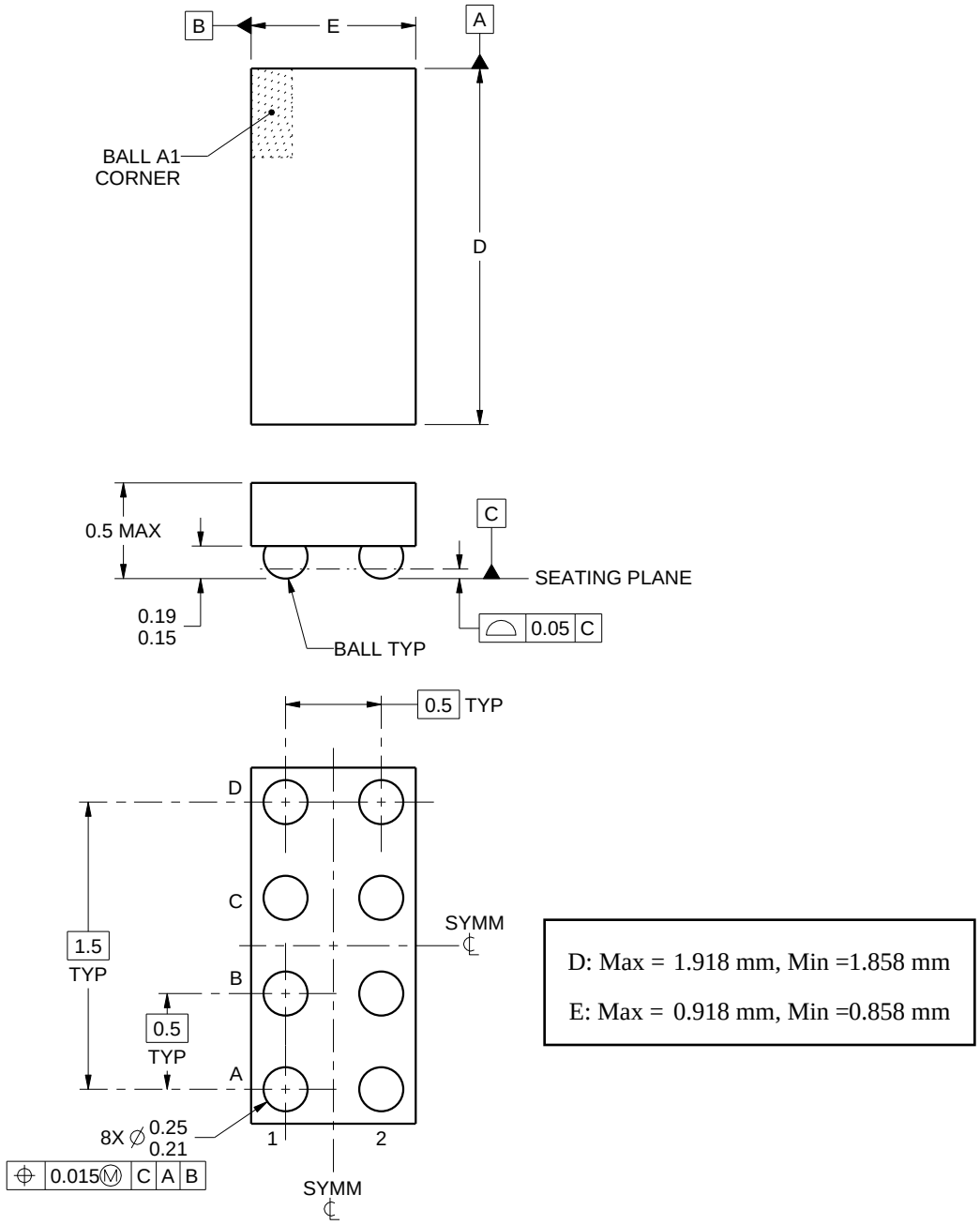
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A3154DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A3154DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A3154DCURG4	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A3154YZPR	DSBGA	YZP	8	3000	220.0	220.0	35.0

PACKAGE OUTLINE

YZP0008

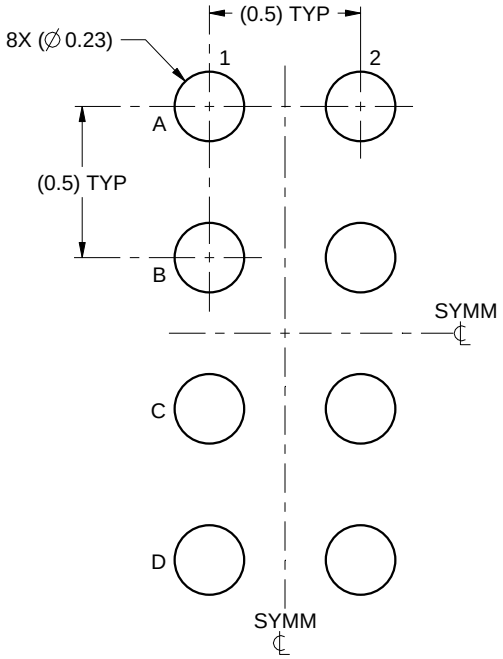
DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY

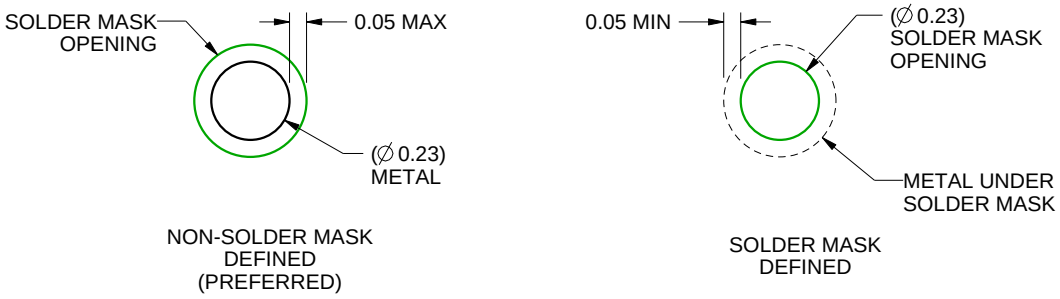


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE:40X

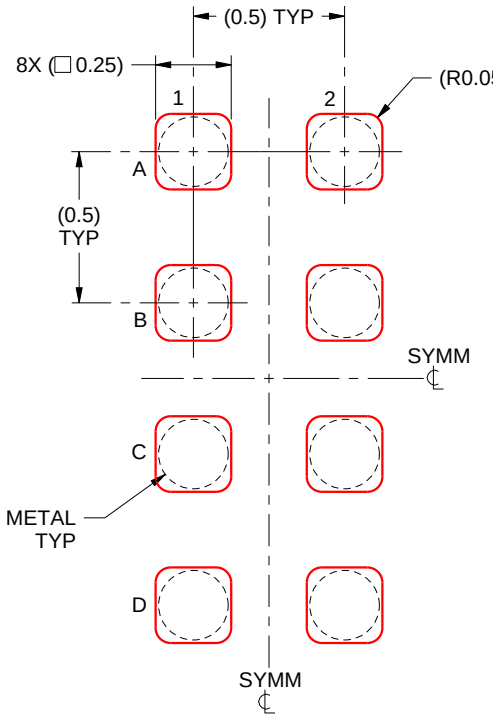


SOLDER MASK DETAILS
NOT TO SCALE

4223082/A 07/2016

NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4223082/A 07/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

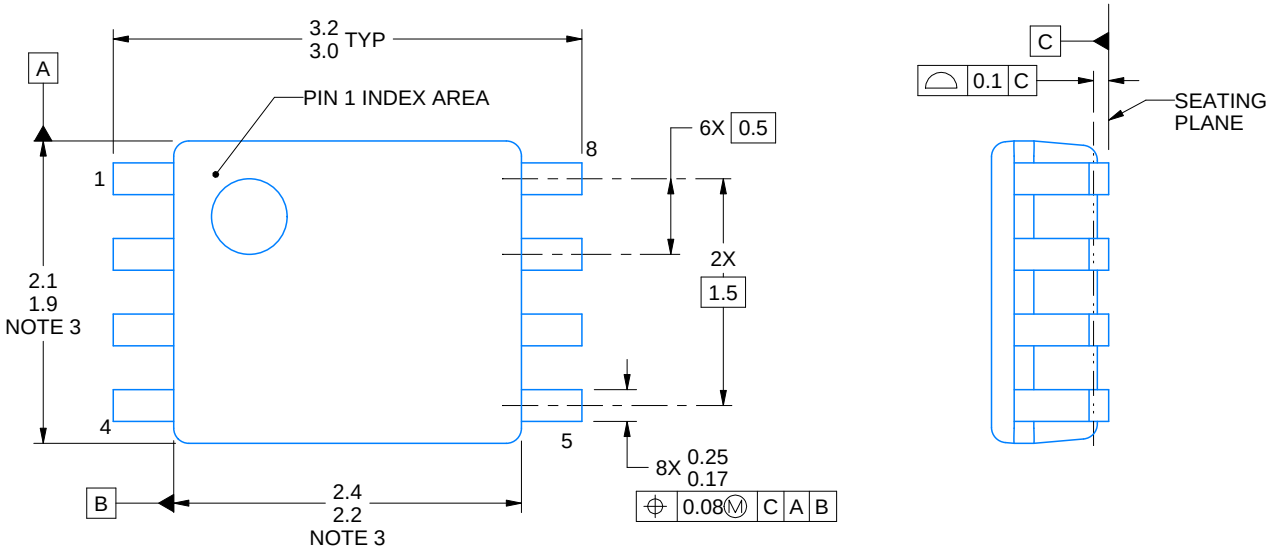
DCU0008A

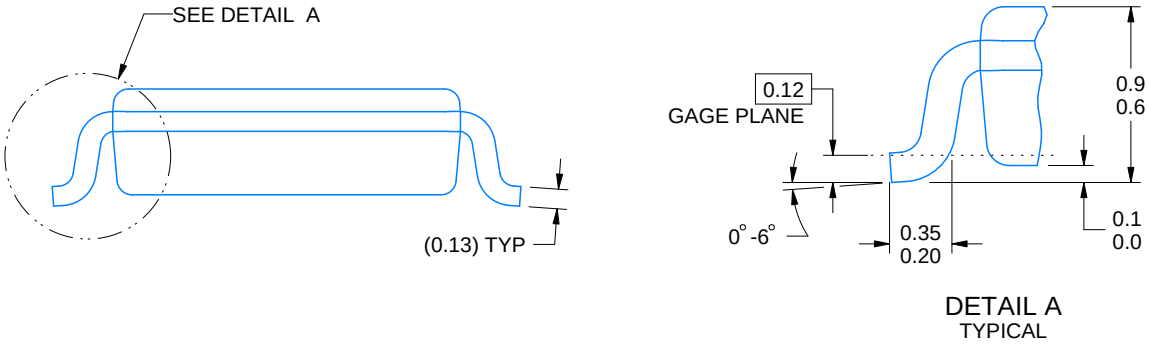


PACKAGE OUTLINE

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE

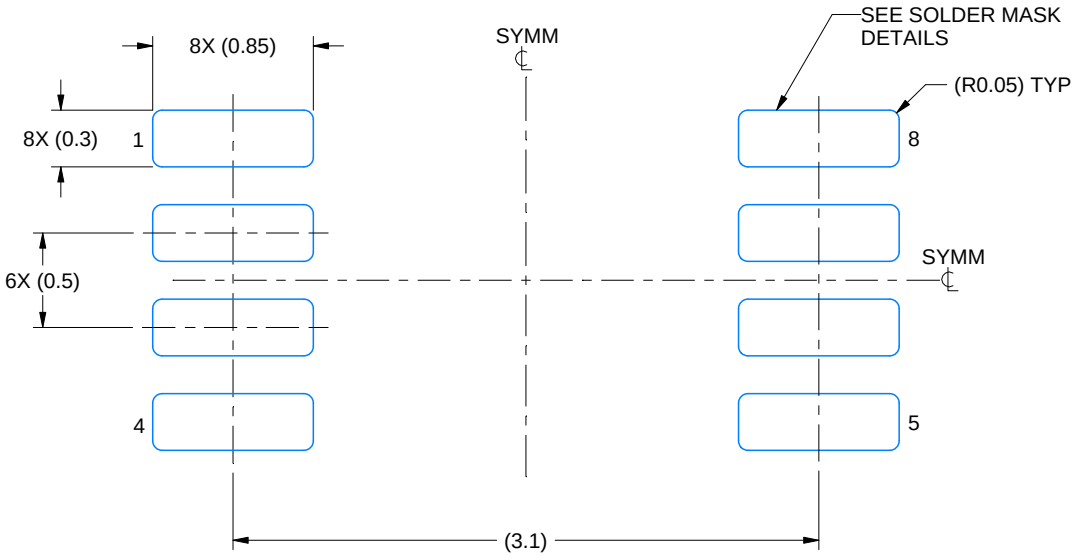




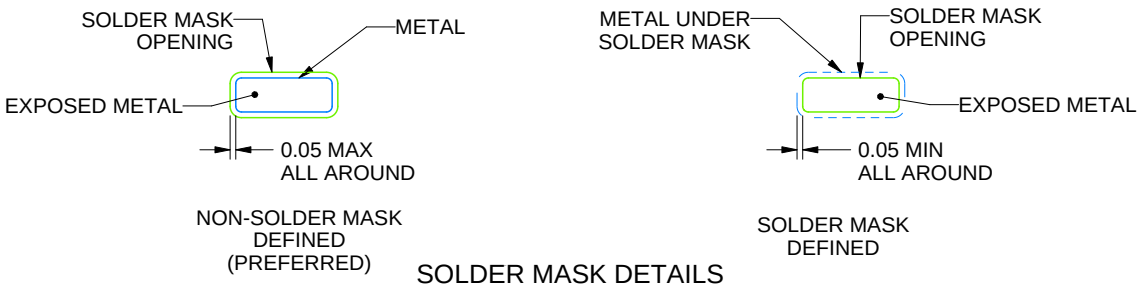
4225266/A 09/2014

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-187 variation CA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X

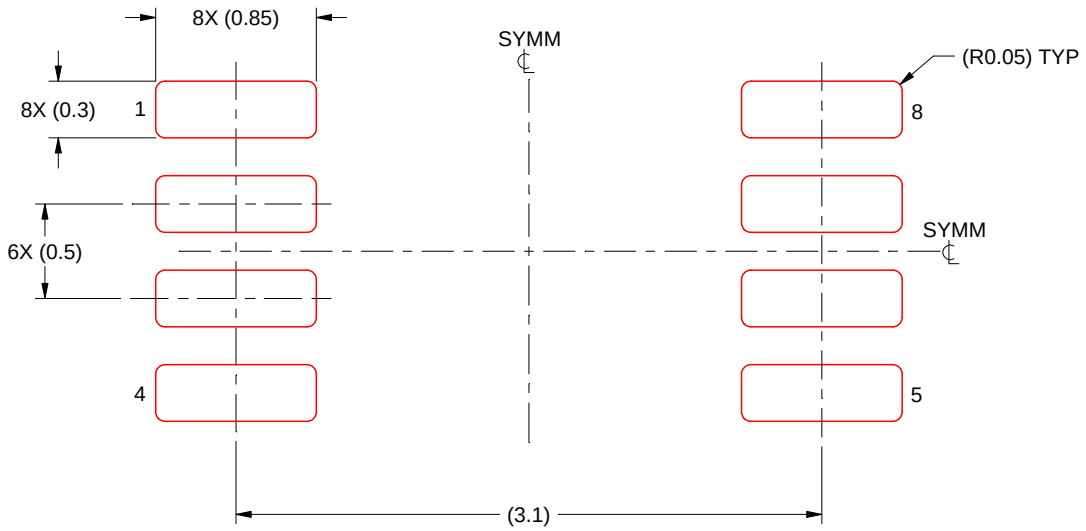


SOLDER MASK DETAILS

4225266/A 09/2014

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 25X

4225266/A 09/2014

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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